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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	7612
Number of Logic Elements/Cells	181165
Total RAM Bits	10177536
Number of I/O	372
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx190ef29c6n

Table 1–3. Maximum Allowed Overshoot During Transitions for Arria II Devices

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
V_I (AC)	AC Input Voltage	4.0	100.000	%
		4.05	79.330	%
		4.1	46.270	%
		4.15	27.030	%
		4.2	15.800	%
		4.25	9.240	%
		4.3	5.410	%
		4.35	3.160	%
		4.4	1.850	%
		4.45	1.080	%
		4.5	0.630	%
		4.55	0.370	%
		4.6	0.220	%

Maximum Allowed I/O Operating Frequency

Table 1–4 lists the maximum allowed I/O operating frequency for Arria II GX I/Os using the specified I/O standards to ensure device reliability.

Table 1–4. Maximum Allowed I/O Operating Frequency for Arria II GX Devices

I/O Standard	I/O Frequency (MHz)
HSTL-18 and HSTL-15	333
SSTL -15	400
SSTL-18	333
2.5-V LVCMOS	260
3.3-V and 3.0-V LVTTTL	250
3.3-V, 3.0-V, 1.8-V, and 1.5-V LVCMOS	
PCI and PCI-X	
SSTL-2	
1.2-V LVCMOS HSTL-12	200

I/O Pin Leakage Current

Table 1-7 lists the Arria II GX I/O pin leakage current specifications.

Table 1-7. I/O Pin Leakage Current for Arria II GX Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0\text{ V to }V_{CCIOMAX}$	-10	—	10	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0\text{ V to }V_{CCIOMAX}$	-10	—	10	μA

Table 1-8 lists the Arria II GZ I/O pin leakage current specifications.

Table 1-8. I/O Pin Leakage Current for Arria II GZ Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0\text{ V to }V_{CCIOMAX}$	-20	—	20	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0\text{ V to }V_{CCIOMAX}$	-20	—	20	μA

Bus Hold

Bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1-9 lists bus hold specifications for Arria II GX devices.

Table 1-9. Bus Hold Parameters for Arria II GX Devices (Note 1)

Parameter	Symbol	Cond.	V _{CCIO} (V)												Unit
			1.2		1.5		1.8		2.5		3.0		3.3		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold low, sustaining current	I _{SUSL}	V _{IN} > V _{IL} (max.)	8	—	12	—	30	—	50	—	70	—	70	—	μA
Bus-hold high, sustaining current	I _{SUSH}	V _{IN} < V _{IL} (min.)	−8	—	−12	—	−30	—	−50	—	−70	—	−70	—	μA
Bus-hold low, overdrive current	I _{ODL}	0 V < V _{IN} < V _{CCIO}	—	125	—	175	—	200	—	300	—	500	—	500	μA
Bus-hold high, overdrive current	I _{ODH}	0 V < V _{IN} < V _{CCIO}	—	−125	—	−175	—	−200	—	−300	—	−500	—	−500	μA
Bus-hold trip point	V _{TRIP}	—	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V

Note to Table 1-9:

(1) The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

Table 1-11. OCT With and Without Calibration Specification for Arria II GX Device I/Os (Note 1) (Part 2 of 2)

Symbol	Description	Conditions (V)	Calibration Accuracy		Unit
			Commercial	Industrial	
50- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2	50- Ω series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 10	± 10	%
100- Ω R_D 2.5	100- Ω differential OCT without calibration	$V_{CCIO} = 2.5$	± 30	± 30	%

Note to Table 1-11:

(1) OCT with calibration accuracy is valid at the time of calibration only.

Table 1-12 lists the OCT termination calibration accuracy specifications for Arria II GZ devices.

Table 1-12. OCT with Calibration Accuracy Specifications for Arria II GZ Devices (Note 1)

Symbol	Description	Conditions (V)	Calibration Accuracy			Unit
			C2	C3,I3	C4,I4	
25- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2 (2)	25- Ω series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 8	± 8	± 8	%
50- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2	50- Ω internal series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 8	± 8	± 8	%
50- Ω R_T 2.5, 1.8, 1.5, 1.2	50- Ω internal parallel OCT with calibration	$V_{CCIO} = 2.5, 1.8,$ 1.5, 1.2	± 10	± 10	± 10	%
20- Ω , 40- Ω , and 60- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2 (3)	20- Ω , 40- Ω and 60- Ω R_S expanded range for internal series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 10	± 10	± 10	%
25- Ω $R_{S_left_shift}$ 3.0, 2.5, 1.8, 1.5, 1.2	25- Ω $R_{S_left_shift}$ internal left shift series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 10	± 10	± 10	%

Notes to Table 1-12:

- (1) OCT calibration accuracy is valid at the time of calibration only.
 (2) 25- Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.
 (3) 20- Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.

The calibration accuracy for calibrated series and parallel OCTs are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Table 1-13 lists the Arria II GZ OCT without calibration resistance tolerance to PVT changes.

Table 1-13. OCT Without Calibration Resistance Tolerance Specifications for Arria II GZ Devices

Symbol	Description	Conditions (V)	Resistance Tolerance		Unit
			C3,I3	C4,I4	
25-Ω R _S 3.0 and 2.5	25-Ω internal series OCT without calibration	V _{CCIO} = 3.0, 2.5	± 40	± 40	%
25-Ω R _S 1.8 and 1.5	25-Ω internal series OCT without calibration	V _{CCIO} = 1.8, 1.5	± 40	± 40	%
25-Ω R _S 1.2	25-Ω internal series OCT without calibration	V _{CCIO} = 1.2	± 50	± 50	%
50-Ω R _S 3.0 and 2.5	50-Ω internal series OCT without calibration	V _{CCIO} = 3.0, 2.5	± 40	± 40	%
50-Ω R _S 1.8 and 1.5	50-Ω internal series OCT without calibration	V _{CCIO} = 1.8, 1.5	± 40	± 40	%
50-Ω R _S 1.2	50-Ω internal series OCT without calibration	V _{CCIO} = 1.2	± 50	± 50	%
100-Ω R _D 2.5	100-Ω internal differential OCT	V _{CCIO} = 2.5	± 25	± 25	%

OCT calibration is automatically performed at power up for OCT-enabled I/Os. When voltage and temperature conditions change after calibration, the resistance may change. Use Equation 1-1 and Table 1-14 to determine the OCT variation when voltage and temperature vary after power-up calibration for Arria II GX and GZ devices.

Equation 1-1. OCT Variation (Note 1)

$$R_{OCT} = R_{SCAL} \left(1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

Notes to Equation 1-1:

- (1) R_{OCT} value calculated from Equation 1-1 shows the range of OCT resistance with the variation of temperature and V_{CCIO}.

Use the following with Equation 1-1:

- R_{SCAL} is the OCT resistance value at power up.
- ΔT is the variation of temperature with respect to the temperature at power up.
- ΔV is the variation of voltage with respect to the V_{CCIO} at power up.
- dR/dT is the percentage change of R_{SCAL} with temperature.
- dR/dV is the percentage change of R_{SCAL} with voltage.

Table 1-14 lists the OCT variation with temperature and voltage after power-up calibration for Arria II GX devices.

Table 1-14. OCT Variation after Power-up Calibration for Arria II GX Devices

Nominal Voltage V_{CCIO} (V)	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.262	0.035
2.5	0.234	0.039
1.8	0.219	0.086
1.5	0.199	0.136
1.2	0.161	0.288

Table 1-15 lists the OCT variation with temperature and voltage after power-up calibration for Arria II GZ devices.

Table 1-15. OCT Variation after Power-Up Calibration for Arria II GZ Devices (Note 1)

Nominal Voltage, V_{CCIO} (V)	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.189	0.0297
2.5	0.208	0.0344
1.8	0.266	0.0499
1.5	0.273	0.0744
1.2	0.317	0.1241

Note to Table 1-15:

(1) Valid for V_{CCIO} range of $\pm 5\%$ and temperature range of 0° to 85°C.

Pin Capacitance

Table 1-16 lists the pin capacitance for Arria II GX devices.

Table 1-16. Pin Capacitance for Arria II GX Devices

Symbol	Description	Typical	Unit
C_{IO}	Input capacitance on I/O pins, dual-purpose pins (differential I/O, clock, R_{up} , R_{dn}), and dedicated clock input pins	7	pF

Table 1–33 lists the differential I/O standard specifications for Arria II GZ devices.

Table 1–33. Differential I/O Standard Specifications for Arria II GZ Devices (Note 1)

I/O Standard (2)	V _{CCIO} (V)			V _{ID} (mV)			V _{ICM(DC)} (V)		V _{OD} (V) (3)			V _{OCM} (V) (3)		
	Min	Typ	Max	Min	Cond.	Max	Min	Max	Min	Typ	Max	Min	Typ	Max
2.5 V LVDS (HIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	1.8	0.247	—	0.6	1.125	1.25	1.375
2.5 V LVDS (VIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	1.8	0.247	—	0.6	1	1.25	1.5
RSDS (HIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.4
RSDS (VIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.5
Mini-LVDS (HIO)	2.375	2.5	2.625	200	—	600	0.4	1.32 5	0.25	—	0.6	1	1.2	1.4
Mini-LVDS (VIO)	2.375	2.5	2.625	200	—	600	0.4	1.32 5	0.25	—	0.6	1	1.2	1.5
LVPECL	2.375	2.5	2.625	300	—	—	0.6	1.8	—	—	—	—	—	—
BLVDS (4)	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—

Notes to Table 1–33:

- (1) 1.4-V/1.5-V PCML transceiver I/O standard specifications are described in “Transceiver Performance Specifications” on page 1–21.
- (2) Vertical I/O (VIO) is top and bottom I/Os; horizontal I/O (HIO) is left and right I/Os.
- (3) R_L range: 90 ≤ R_L ≤ 110 Ω.
- (4) There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. These specifications depend on the system topology.

Power Consumption for the Arria II Device Family

Altera offers two ways to estimate power for a design:

- Using the Microsoft Excel-based Early Power Estimator
- Using the Quartus® II PowerPlay Power Analyzer feature

The interactive Microsoft Excel-based Early Power Estimator is typically used prior to designing the FPGA in order to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after place-and-route is complete. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities which, when combined with detailed circuit models, can yield very accurate power estimates.



For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in volume 3 of the *Quartus II Handbook*.

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 4 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Minimum peak-to-peak differential input voltage V_{ID} (diff p-p)	—	100	—	—	100	—	—	100	—	—	100	—	—	mV
V_{ICM}	$V_{ICM} = 0.82$ V setting	—	820	—	—	820	—	—	820	—	—	820	—	mV
	$V_{ICM} = 1.1$ V setting (7)	—	1100	—	—	1100	—	—	1100	—	—	1100	—	mV
Differential on-chip termination resistors	100- Ω setting	—	100	—	—	100	—	—	100	—	—	100	—	Ω
Return loss differential mode	PCIe				50 MHz to 1.25 GHz: –10dB									
	XAU1				100 MHz to 2.5 GHz: –10dB									
Return loss common mode	PCIe				50 MHz to 1.25 GHz: –6dB									
	XAU1				100 MHz to 2.5 GHz: –6dB									
Programmable PPM detector (8)	—	$\pm 62.5, 100, 125, 200, 250, 300, 500, 1000$												ppm
Run length	—	—	80	—	—	80	—	—	80	—	—	80	—	UI
Programmable equalization	—	—	—	7	—	—	7	—	—	7	—	—	7	dB
Signal detect/loss threshold	PCIe Mode	65	—	175	65	—	175	65	—	175	65	—	175	mV
CDR LTR time (9)	—	—	—	75	—	—	75	—	—	75	—	—	75	μ s
CDR minimum T1b (10)	—	15	—	—	15	—	—	15	—	—	15	—	—	μ s

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 5 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
-3 dB Bandwidth	PCIe Gen1	2.5 - 3.5						MHz
	PCIe Gen2	6 - 8						MHz
	(OIF) CEI PHY at 4.976 Gbps	7 - 11						MHz
	(OIF) CEI PHY at 6.375 Gbps	5 - 10						MHz
	XAUI	2 - 4						MHz
	SRIO 1.25 Gbps	3 - 5.5						MHz
	SRIO 2.5 Gbps	3 - 5.5						MHz
	SRIO 3.125 Gbps	2 - 4						MHz
	GIGE	2.5 - 4.5						MHz
	SONET OC12	1.5 - 2.5						MHz
	SONET OC48	3.5 - 6						MHz
Transceiver-FPGA Fabric Interface								
Interface speed	—	25	—	325	25	—	250	MHz
Digital reset pulse width	—	Minimum is two parallel clock cycles						—

Notes to Table 1–35:

- (1) The 3x speed grade is the fastest speed grade offered in the following Arria II GZ devices: EP2AGZ225, EP2AGZ300, and EP2AGZ350.
- (2) The rise and fall time transition is specified from 20% to 80%.
- (3) To calculate the REFCLK rms phase jitter requirement at reference clock frequencies other than 100 MHz, use the following formula:
REFCLK rms phase jitter at f (MHz) = REFCLK rms phase jitter at 100 MHz * 100/f.
- (4) The minimum `reconfig_clk` frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter only** mode. The minimum `reconfig_clk` frequency is 37.5 MHz if the transceiver channel is configured in **Receiver only** or **Receiver and Transmitter** mode.
- (5) If your design uses more than one dynamic reconfiguration controller (`altgx_reconfig`) instances to control the transceiver (`altgx`) channels physically located on the same side of the device AND if you use different `reconfig_clk` sources for these `altgx_reconfig` instances, the delta time between any two of these `reconfig_clk` sources becoming stable must not exceed the maximum specification listed.
- (6) The device cannot tolerate prolonged operation at this absolute maximum.
- (7) You must use the 1.1-V RX V_{ICM} setting if the input serial data standard is LVDS.
- (8) The differential eye opening specification at the receiver input pins assumes that Receiver Equalization is disabled. If you enable Receiver Equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level. Use H-Spice simulation to derive the minimum eye opening requirement with Receiver Equalization enabled.
- (9) The rate matcher supports only up to ± 300 ppm.
- (10) Time taken to `rx_pll_locked` goes high from `rx_analogreset` de-assertion. Refer to [Figure 1–1 on page 1–33](#).
- (11) Time for which the CDR must be kept in lock-to-reference mode after `rx_pll_locked` goes high and before `rx_locktodata` is asserted in manual mode. Refer to [Figure 1–1 on page 1–33](#).
- (12) Time taken to recover valid data after the `rx_locktodata` signal is asserted in manual mode. Refer to [Figure 1–1 on page 1–33](#).
- (13) Time taken to recover valid data after the `rx_freqlocked` signal goes high in automatic mode. Refer to [Figure 1–2 on page 1–33](#).
- (14) A GPLL may be required to meet the PMA-FPGA fabric interface timing above certain data rates. For more information, refer to the [Transceiver Clocking for Arria II Devices](#) chapter.
- (15) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (16) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Table 1–39. Transmitter Pre-Emphasis Levels for Arria II GZ Devices (Part 2 of 2)

Pre-Emphasis 1st Post-Tap Setting	V _{DD} Setting							
	0	1	2	3	4	5	6	7
29	N/A	N/A	N/A	12.5	9.6	7.7	6.3	4.3
30	N/A	N/A	N/A	N/A	11.4	9	7.4	N/A
31	N/A	N/A	N/A	N/A	12.9	10	8.2	N/A

Table 1–40 lists the transceiver jitter specifications for all supported protocols for Arria II GX devices.

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 1 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
SONET/SDH Transmit Jitter Generation (2)														
Peak-to-peak jitter at 622.08 Mbps	Pattern = PRBS15	—	—	0.1	—	—	0.1	—	—	0.1	—	—	0.1	UI
RMS jitter at 622.08 Mbps	Pattern = PRBS15	—	—	0.01	—	—	0.01	—	—	0.01	—	—	0.01	UI
Peak-to-peak jitter at 2488.32 Mbps	Pattern = PRBS15	—	—	0.1	—	—	0.1	—	—	0.1	—	—	0.1	UI
RMS jitter at 2488.32 Mbps	Pattern = PRBS15	—	—	0.01	—	—	0.01	—	—	0.01	—	—	0.01	UI
SONET/SDH Receiver Jitter Tolerance (2)														
Jitter tolerance at 622.08 Mbps	Jitter frequency = 0.03 KHz Pattern = PRBS15	> 15			> 15			> 15			> 15			UI
	Jitter frequency = 25 KHZ Pattern = PRBS15	> 1.5			> 1.5			> 1.5			> 1.5			UI
	Jitter frequency = 250 KHz Pattern = PRBS15	> 0.15			> 0.15			> 0.15			> 0.15			UI

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 6 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 20 KHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar		> 1			> 1			> 1			> 1		UI
	Jitter frequency = 100 KHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar		> 0.2			> 0.2			> 0.2			> 0.2		UI
	Jitter frequency = 148.5 MHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar		> 0.2			> 0.2			> 0.2			> 0.2		UI
SATA Transmit Jitter Generation (10)														
Total jitter at 1.5 Gbps (G1)	Compliance pattern	—	—	0.55	—	—	0.55	—	—	0.55	—	—	0.55	UI
Deterministic jitter at 1.5 Gbps (G1)	Compliance pattern	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Total jitter at 3.0 Gbps (G2)	Compliance pattern	—	—	0.55	—	—	0.55	—	—	0.55	—	—	0.55	UI
Deterministic jitter at 3.0 Gbps (G2)	Compliance pattern	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Total jitter at 6.0 Gbps (G3)	Compliance pattern	—	—	0.52	—	—	—	—	—	—	—	—	—	UI
Random jitter at 6.0 Gbps (G3)	Compliance pattern	—	—	0.18	—	—	—	—	—	—	—	—	—	UI
SATA Receiver Jitter Tolerance (10)														
Total jitter tolerance at 1.5 Gbps (G1)	Compliance pattern		> 0.65			> 0.65			> 0.65			> 0.65		UI
Deterministic jitter tolerance at 1.5 Gbps (G1)	Compliance pattern		> 0.35			> 0.35			> 0.35			> 0.35		UI
SSC modulation frequency at 1.5 Gbps (G1)	Compliance pattern		33			33			33			33		kHz

Table 1-40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 8 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
CPRI Transmit Jitter Generation (11)														
Total jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.27 9	—	—	0.279	—	—	0.279	—	—	0.279	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Deterministic jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.14	—	—	0.14	—	—	0.14	—	—	0.14	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI
CPRI Receiver Jitter Tolerance (11)														
Total jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.66			> 0.66			> 0.66			> 0.66			UI
Deterministic jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.4			> 0.4			> 0.4			> 0.4			UI
Total jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.65			> 0.65			> 0.65			> 0.65			UI
	E.60.LV Pattern = PRBS31	> 0.6			—			—			—			UI
Deterministic jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.37			> 0.37			> 0.37			> 0.37			UI
	E.60.LV Pattern = PRBS31	> 0.45			—			—			—			UI
Combined deterministic and random jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.55			> 0.55			> 0.55			> 0.55			UI
OBSAI Transmit Jitter Generation (12)														
Total jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern = CJPAT	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Deterministic jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 6 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Deterministic jitter at 3.0 Gbps (G2)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Total jitter at 6.0 Gbps (G3)	Pattern = CJPAT	—	—	0.25	—	—	0.25	UI
Random jitter at 6.0 Gbps (G3)	Pattern = CJPAT	—	—	0.15	—	—	0.15	UI
SAS Receiver Jitter Tolerance (13)								
Total jitter tolerance at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.65	—	—	0.65	UI
Deterministic jitter tolerance at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Sinusoidal jitter tolerance at 1.5 Gbps (G1)	Jitter frequency = 900 KHz to 5 MHz Pattern = CJTPAT BER = 1E-12	> 0.1			> 0.1			UI
CPRI Transmit Jitter Generation (14)								
Total jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.279	—	—	0.279	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Deterministic jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.14	—	—	0.14	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	—	—	0.17	—	—	0.17	UI
CPRI Receiver Jitter Tolerance (14)								
Total jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.66			> 0.66			UI
Deterministic jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.4			> 0.4			UI
Total jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.65			> 0.65			UI
Deterministic jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.55			> 0.55			UI
OBSAI Transmit Jitter Generation (15)								
Total jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern CJPAT	—	—	0.35	—	—	0.35	UI
Deterministic jitter at 768 MBps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern CJPAT	—	—	0.17	—	—	0.17	UI

DSP Block Specifications

Table 1-46 lists the DSP block performance specifications for Arria II GX devices.

Table 1-46. DSP Block Performance Specifications for Arria II GX Devices (Note 1)

Mode	Resources Used	Performance				Unit
	Number of Multipliers	C4	I3	C5,I5	C6	
9 × 9-bit multiplier	1	380	310	300	250	MHz
12 × 12-bit multiplier	1	380	310	300	250	MHz
18 × 18-bit multiplier	1	380	310	300	250	MHz
36 × 36-bit multiplier	1	350	270	270	220	MHz
18 × 36-bit high-precision multiplier adder mode	1	350	270	270	220	MHz
18 × 18-bit multiply accumulator	4	380	310	300	250	MHz
18 × 18-bit multiply adder	4	380	310	300	250	MHz
18 × 18-bit multiply adder-signed full precision	2	380	310	300	250	MHz
18 × 18-bit multiply adder with loopback (2)	2	275	220	220	180	MHz
36-bit shift (32-bit data)	1	350	270	270	220	MHz
Double mode	1	350	270	270	220	MHz

Notes to Table 1-46:

- (1) Maximum is for a fully-pipelined block with **Round** and **Saturation** disabled.
- (2) Maximum is for loopback input registers disabled, **Round** and **Saturation** disabled, pipeline and output registers enabled.

Table 1-47 lists the DSP block performance specifications for Arria II GZ devices.

Table 1-47. DSP Block Performance Specifications for Arria II GZ Devices (Note 1) (Part 1 of 2)

Mode	Resources Used	Performance		Unit
	Number of Multipliers	-3	-4	
9 × 9-bit multiplier	1	460	400	MHz
12 × 12-bit multiplier	1	500	440	MHz
18 × 18-bit multiplier	1	550	480	MHz
36 × 36-bit multiplier	1	440	380	MHz
18 × 18-bit multiply accumulator	4	440	380	MHz
18 × 18-bit multiply adder	4	470	410	MHz
18 × 18-bit multiply adder-signed full precision	2	450	390	MHz
18 × 18-bit multiply adder with loopback (2)	2	350	310	MHz
36-bit shift (32-bit data)	1	440	380	MHz

Table 1-53. High-Speed I/O Specifications for Arria II GX Devices (Part 3 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{TX_JITTER} (4)	True LVDS with dedicated SERDES (data rate 600–1,250 Mbps)	—	175	—	175	—	225	—	300	ps
	True LVDS with dedicated SERDES (data rate < 600 Mbps)	—	0.105	—	0.105	—	0.135	—	0.18	UI
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate 600 – 945 Mbps)	—	260	—	260	—	300	—	350	ps
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate < 600 Mbps)	—	0.16	—	0.16	—	0.18	—	0.21	UI
t_{TX_DCD}	True LVDS and emulated LVDS_E_3R	45	55	45	55	45	55	45	55	%
t_{RISE} and t_{FALL}	True LVDS and emulated LVDS_E_3R	—	200	—	200	—	225	—	250	ps
TCCS	True LVDS (5)	—	150	—	150	—	175	—	200	ps
	Emulated LVDS_E_3R	—	200	—	200	—	250	—	300	ps
Receiver (6)										
True differential I/O standards - f_{HSDRPA} (data rate)	SERDES factor J = 3 to 10	150	1250	150	1250	150	1050	150	840	Mbps

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 3 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
$t_{RISE} \& t_{FALL}$	True differential I/O standards	—	—	200	—	—	200	ps
	Emulated differential I/O standards with three external output resistor networks	—	—	250	—	—	300	ps
	Emulated differential I/O standards with one external output resistor	—	—	500	—	—	500	ps
TCCS	True LVDS	—	—	100	—	—	100	ps
	Emulated LVDS_E_3R	—	—	250	—	—	250	ps
Receiver								
True differential I/O standards - f_{HSDRDP} (data rate)	SERDES factor J = 3 to 10	150	—	1250	150	—	1250	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(4)	—	(6)	(4)	—	(6)	Mbps
	SERDES factor J = 2, uses DDR registers	(4)	—	(5)	(4)	—	(5)	Mbps
	SERDES factor J = 1, uses an SDR register	(4)	—	(5)	(4)	—	(5)	Mbps
DPA run length	DPA mode	—	—	10000	—	—	10000	UI
Soft-CDR PPM tolerance	Soft-CDR mode	—	—	300	—	—	300	± PPM
Sampling Window (SW)	Non-DPA mode	—	—	300	—	—	300	ps

Notes to Table 1–54:

- (1) When J = 3 to 10, use the SERDES block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) Clock Boost Factor (W) is the ratio between input data rate to the input clock rate.
- (4) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (5) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (6) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and the receiver sampling margin to determine the maximum data rate supported.
- (7) This is achieved by using the LVDS and DPA clock network.
- (8) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (9) This only applies to DPA and soft-CDR modes.
- (10) This only applies to LVDS source synchronous mode.

Table 1–55 lists DPA lock time specifications for Arria II GX and GZ devices.

Figure 1-6 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for Arria II GZ devices at 1.25 Gbps data rate.

Figure 1-6. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for Arria II GZ Devices at a 1.25 Gbps Data Rate

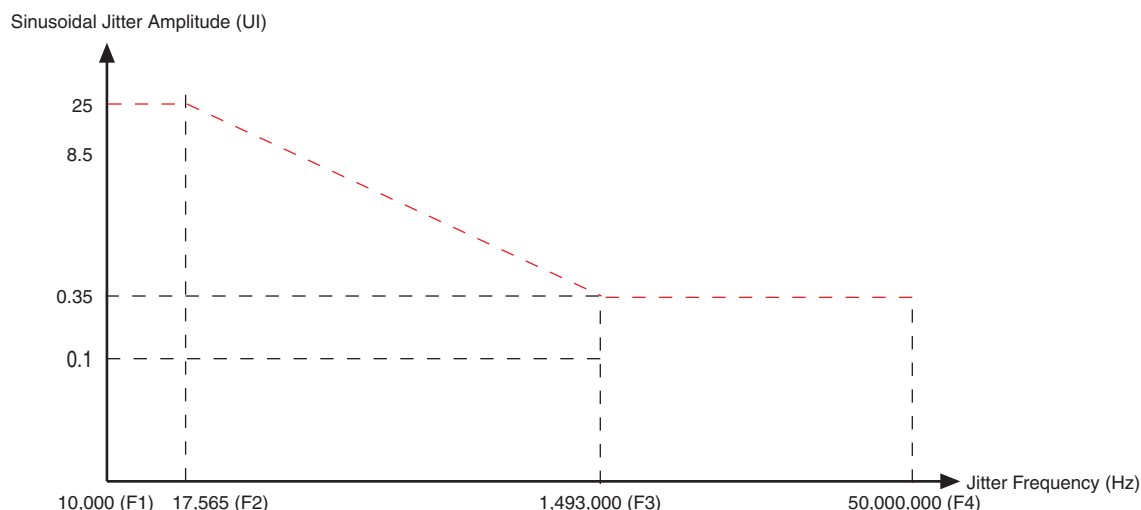


Table 1-56 lists the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for Arria II GZ devices at 1.25 Gbps data rate.

Table 1-56. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for Arria II GZ Devices at 1.25 Gbps Data Rate

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

External Memory Interface Specifications

 For the maximum clock rate supported for Arria II GX and GZ device family, refer to the [External Memory Interface Spec Estimator](#) page on the Altera website.

Table 1-57 lists the external memory interface specifications for Arria II GX devices.

Table 1-57. External Memory Interface Specifications for Arria II GX Devices (Part 1 of 2)

Frequency Mode	Frequency Range (MHz)			Resolution (°)	DQS Delay Buffer Mode ⁽¹⁾	Number of Delay Chains
	C4	I3, C5, I5	C6			
0	90-140	90-130	90-110	22.5	Low	16
1	110-180	110-170	110-150	30	Low	12
2	140-220	140-210	140-180	36	Low	10
3	170-270	170-260	170-220	45	Low	8
4	220-340	220-310	220-270	30	High	12

Table 1-57. External Memory Interface Specifications for Arria II GX Devices (Part 2 of 2)

Frequency Mode	Frequency Range (MHz)			Resolution (°)	DQS Delay Buffer Mode (1)	Number of Delay Chains
	C4	I3, C5, I5	C6			
5	270-410	270-380	270-320	36	High	10
6	320-450	320-410	320-370	45	High	8

Note to Table 1-57:

(1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1-58 lists the DLL frequency range specifications for Arria II GZ devices.

Table 1-58. DLL Frequency Range Specifications for Arria II GZ Devices

Frequency Mode	Frequency Range (MHz)		Available Phase Shift	DQS Delay Buffer Mode (1)	Number of Delay Chains
	-3	-4			
0	90-130	90-120	22.5°, 45°, 67.5°, 90°	Low	16
1	120-170	120-160	30°, 60°, 90°, 120°	Low	12
2	150-210	150-200	36°, 72°, 108°, 144°	Low	10
3	180-260	180-240	45°, 90°, 135°, 180°	Low	8
4	240-320	240-290	30°, 60°, 90°, 120°	High	12
5	290-380	290-360	36°, 72°, 108°, 144°	High	10
6	360-450	360-450	45°, 90°, 135°, 180°	High	8
7	470-630	470-590	60°, 120°, 180°, 240°	High	6

Note to Table 1-58:

(1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1-59 lists the DQS phase offset delay per stage for Arria II GX devices.

Table 1-59. DQS Phase Offset Delay Per Setting for Arria II GX Devices (Note 1), (2), (3)

Speed Grade	Min	Max	Unit
C4	7.0	13.0	ps
I3, C5, I5	7.0	15.0	ps
C6	8.5	18.0	ps

Notes to Table 1-59:

- (1) The valid settings for phase offset are -64 to +63 for frequency modes 0 to 3 and -32 to +31 for frequency modes 4 to 5.
- (2) The typical value equals the average of the minimum and maximum values.
- (3) The delay settings are linear.

Table 1-63 lists the memory output clock jitter specifications for Arria II GZ devices.

Table 1-63. Memory Output Clock Jitter Specification for Arria II GZ Devices (Note 1), (2), (3)

Parameter	Clock Network	Symbol	-3		-4		Unit
			Min	Max	Min	Max	
Clock period jitter	Regional	$t_{JIT(per)}$	-55	55	-55	55	ps
Cycle-to-cycle period jitter	Regional	$t_{JIT(cc)}$	-110	110	-110	110	ps
Duty cycle jitter	Regional	$t_{JIT(duty)}$	-82.5	82.5	-82.5	82.5	ps
Clock period jitter	Global	$t_{JIT(per)}$	-82.5	82.5	-82.5	82.5	ps
Cycle-to-cycle period jitter	Global	$t_{JIT(cc)}$	-165	165	-165	165	ps
Duty cycle jitter	Global	$t_{JIT(duty)}$	-90	90	-90	90	ps

Notes to Table 1-63:

- (1) The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard.
- (2) The clock jitter specification applies to memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a regional or global clock network as specified. Altera recommends using regional clock networks whenever possible.
- (3) The memory output clock jitter stated in Table 1-63 is applicable when an input jitter of 30 ps is applied.

Duty Cycle Distortion (DCD) Specifications

Table 1-64 lists the worst-case DCD specifications for Arria II GX devices.

Table 1-64. Duty Cycle Distortion on I/O Pins for Arria II GX Devices (Note 1)

Symbol	C4		I3, C5, I5		C6		Unit
	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	%

Note to Table 1-64:

- (1) The DCD specification applies to clock outputs from the PLL, global clock tree, IOE driving dedicated, and general purpose I/O pins.

Table 1-65 lists the worst-case DCD specifications for Arria II GZ devices.

Table 1-65. Duty Cycle Distortion on I/O Pins for Arria II GZ Devices (Note 1)

Symbol	C3, I3		C4, I4		Unit
	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	%

Note to Table 1-65:

- (1) The DCD specification applies to clock outputs from the PLL, global clock tree, IOE driving dedicated, and general purpose I/O pins.

Table 1-68. Glossary (Part 2 of 4)

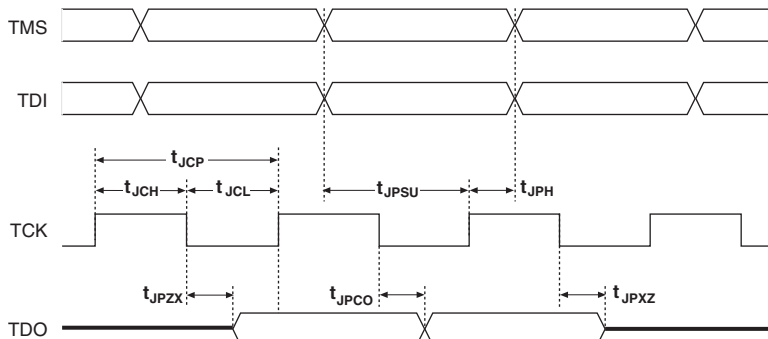
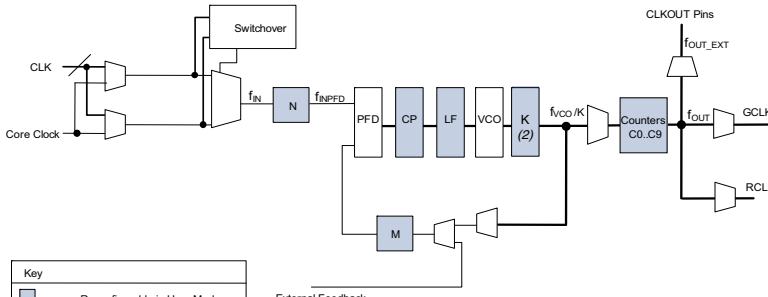
Letter	Subject	Definitions
G, H, I, J	J	High-speed I/O block: Deserialization factor (width of parallel data bus).
	JTAG Timing Specifications	JTAG Timing Specifications: 
K, L, M, N, O, P	PLL Specifications	PLL Specification parameters: Diagram of PLL Specifications (1)  Notes: (1) CoreClock can only be fed by dedicated clock input pins or PLL outputs. (2) This is the VCO post-scale counter K.
Q, R	R _L	Receiver differential input discrete resistor (external to the Arria II device).

Table 1–68. Glossary (Part 4 of 4)

Letter	Subject	Definitions
U, V	$V_{CM(DC)}$	DC common mode input voltage.
	V_{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.
	V_{ID}	Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage: Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage: Minimum DC input differential voltage required for switching.
	V_{IH}	Voltage input high: The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage.
	$V_{IH(DC)}$	High-level DC input voltage.
	V_{IL}	Voltage input low: The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage.
	$V_{IL(DC)}$	Low-level DC input voltage.
	V_{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.
	V_{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
W, X, Y, Z	W	High-speed I/O block: The clock boost factor.

Document Revision History

Table 1–69 lists the revision history for this chapter.

Table 1–69. Document Revision History (Part 1 of 2)

Date	Version	Changes
December 2013	4.4	Updated Table 1–34 and Table 1–35.
July 2012	4.3	- Updated the $V_{CCH_GXBL/R}$ operating conditions in Table 1–6. - Finalized Arria II GZ information in Table 1–20. - Added BLVDS specification in Table 1–32 and Table 1–33. - Updated input and output waveforms in Table 1–68.
December 2011	4.2	- Updated Table 1–32, Table 1–33, Table 1–34, Table 1–35, Table 1–40, Table 1–41, Table 1–54, and Table 1–67. - Minor text edits.
June 2011	4.1	- Added Table 1–60. - Updated Table 1–32, Table 1–33, Table 1–38, Table 1–41, and Table 1–61. - Updated the “Switching Characteristics” section introduction. - Minor text edits.